



RAYSTAR

曜凌光電股份有限公司

住址: 42878 台中市大雅区科雅路 25 號 5F WEB: <http://www.Raystar-Optronics.com>
5F., No.25, Keya Rd., Daya Dist., Taichung E-mail: sales@raystar-optronics.com
City 428, Taiwan Tel:886-4-2565-0761 Fax : 886-4-2565-0760

RFP620A-6XW-DNN

SPECIFICATION

CUSTOMER:

APPROVED BY	
PCB VERSION	
DATE	

FOR CUSTOMER USE ONLY

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

Release DATE:

Revision History

VERSION	DATE	REVISED PAGE NO.	Note
0 A	2015/10/14 2016/01/21		First issue Modify Static electricity test

Contents

1.Module Classification Information

2.Summary

3.General Specification

4.Interface

5.Contour Drawing

6.Block Diagram

7.Absolute Maximum Ratings

8.Electrical Characteristics

9.DC Characteristics

10.AC Characteristics

11.Optical Characteristics

12.Reliability

13.Package Specification

14.Initial Code For Reference

15.Other

1.Module Classification Information

R	F	P	62	0A	-	6	X	W	-	D	N	N
1	2	3	4	5	-	6	7	8	-	9	10	11

Item	Description	
1	R : Raystar Optonics Inc.	
2	Display Type : F→TFT Type, J→ Custom TFT	
3	Solution: A: 128x160 B:320x234 C:320x240 D:480x234 E:480x272 F:800x480 G:640x480 H:1024x600 I:320x480 J:240x320 K:1280x800 L:240x400 M:1024x768 N:128x128 O:480x800 P:640x320 Q:800x600 S:480x128 T:800x320	
4	Display Size : 6.2" TFT	
5	Version Code.	
6	Model Type: A : TFT LCD E : TFT+FR+CONTROL BOARD J : TFT+FR+A/D BOARD N : TFT+FR+A/D BOARD+CONTROL BOARD S : TFT+FR+POWER BOARD (DC TO DC) 1 : TFT+CONTROL BOARD	6 : TFT+FR H : TFT+D/V BOARD I : TFT+FR+D/V BOARD B : TFT+POWER BD
7	Polarizer Type, Temperature range, View direction	I→Transmissive, W. T, 6:00 ; C→Transmissive, N. T, 6:00 L→Transmissive, W.T,12:00 ; F→Transmissive, N.T,12:00 Y→Transmissive,W.T, IPS TFT ; A→Transmissive, N.T, IPS TFT Z→Transmissive, W.T, O-TFT R→Transmissive, Super W.T, O-TFT N→Transmissive, Super W.T, 6:00; Q→Transmissive, Super W.T, 12:00 V→Transmissive, Super W.T, VA TFT
8	Backlight	W : LED, White H : LED, High Light White F : CCFL, White
9	Driver Method	D: Digital A: Analog L : LVDS M:MIPI
10	Interface	N : without control board A : 8Bit B : 16Bit S:SPI Interface R: RS232 U:USB I: I2C
11	TS	N : Without TS S : resistive touch panel C : capacitive touch panel capacitive touch panel (G-F-F) G : capacitive touch panel(G-G)

2.Summary

This technical specification applies to 6.2' Mono TFT-LCD panel. The 6.2' Mono TFT-LCD panel is designed for camcorder, digital camera application and other electronic products which require high quality flat panel displays. This module follows RoHS.

RAYSTAR OPTRONICS

3.General Specifications

- Size: 6.2 inch
- Dot Matrix: 640 x 320 dots
- Module dimension: 170.32 x 88.3 x 5.3 mm
- Active area: 140 x 70 mm
- Dot pitch: 0.21875 x 0. 21875 mm
- LCD type: TFT, Normally Black, Transmissive
- View Direction: Wide View
- Gray Scale: 16 Gray scale (4BPP)/ 4 Gray scale (2BPP)/ 2 Gray scale (1BPP)
- Controller IC: ST7511U
- Backlight Type: LED, Normally White
- With /Without TP: Without TP
- Surface: Glare

* Mono tone slight changed by temperature and driving voltage.

4.Interface

4.1. LCM PIN Definition

Pin	Symbol	Function	Remark
1	GND	System ground	
2	VDD	Power Supply : +3.3V	
3	NC	No connect	
4	A0	Data/Command select	
5	/WR(R/W)	Write strobe signal	
6	/RD(E)	Read strobe signal	
7	DB0	Data bus	
8	DB1	Data bus	
9	DB2	Data bus	
10	DB3	Data bus	
11	DB4	Data bus	
12	DB5	Data bus	
13	DB6	Data bus	
14	DB7	Data bus	
15	/CS	Chip select	
16	/RESET(RSTB)	Hardware reset	
17	IF0	Mode select	Note1
18	IF1		
19	NC	No connect	
20	NC	No connect	
21	NC	No connect	
22	NC	No connect	

Note1:

Setting		MCU Type	Interface Pin Function				
IF1	IF0		CSB	A0	RWR	ERD	D[7:0]
L	L	Parallel 8080 series MCU	CSB	A0	/WR	/RD	D[7:0]
L	H	Parallel 6800 series MCU			R/W	E	
H	H	Serial 4-Line series MCU			-	-	D7=SCL, D0=SDA, D[6:1] are not used
H	L	Serial 3-Line series MCU			-	-	

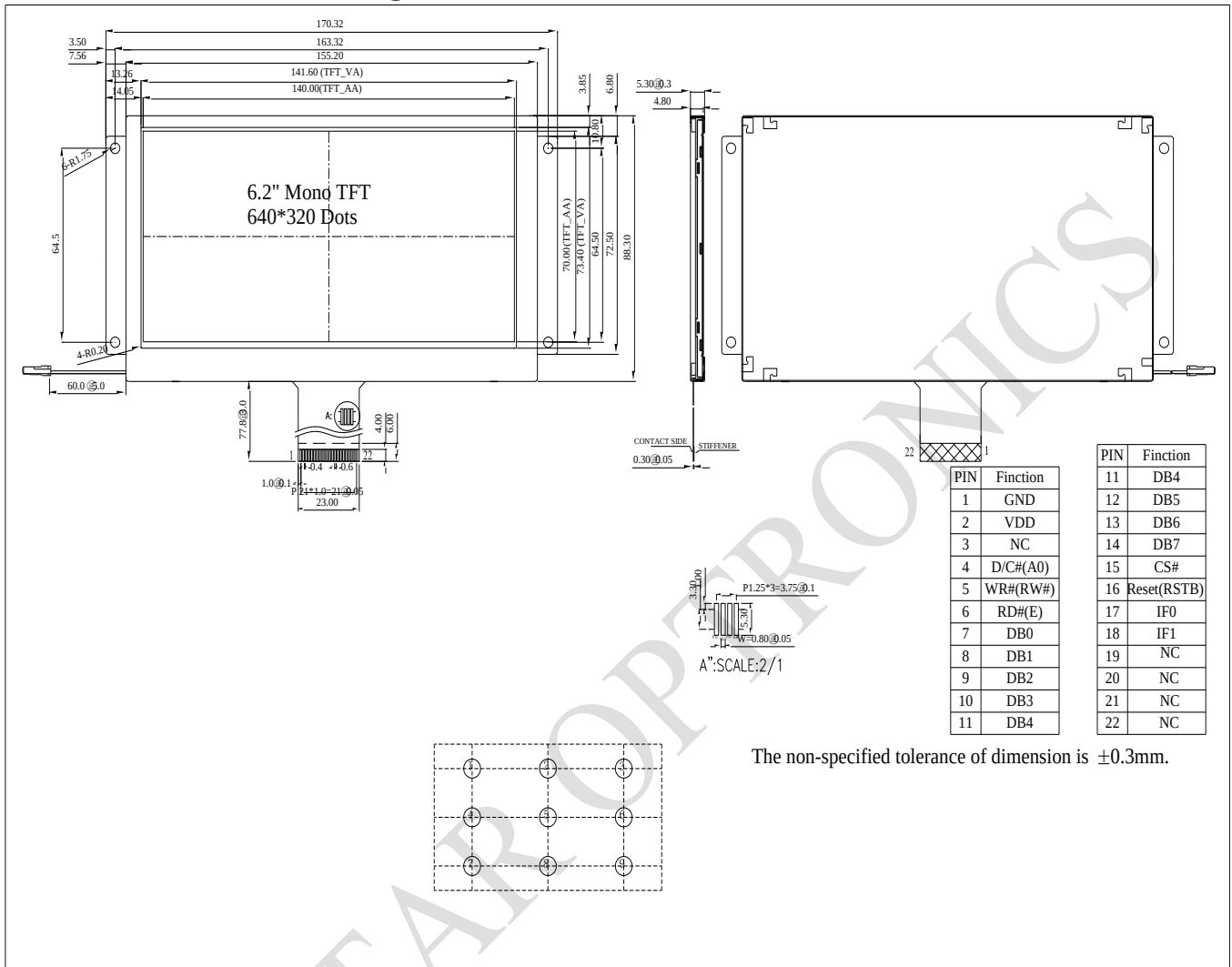
The un-used pins are marked as “-” and should be connected to “H” by VDDI.

4.2. Backlight Unit Section(CN2)

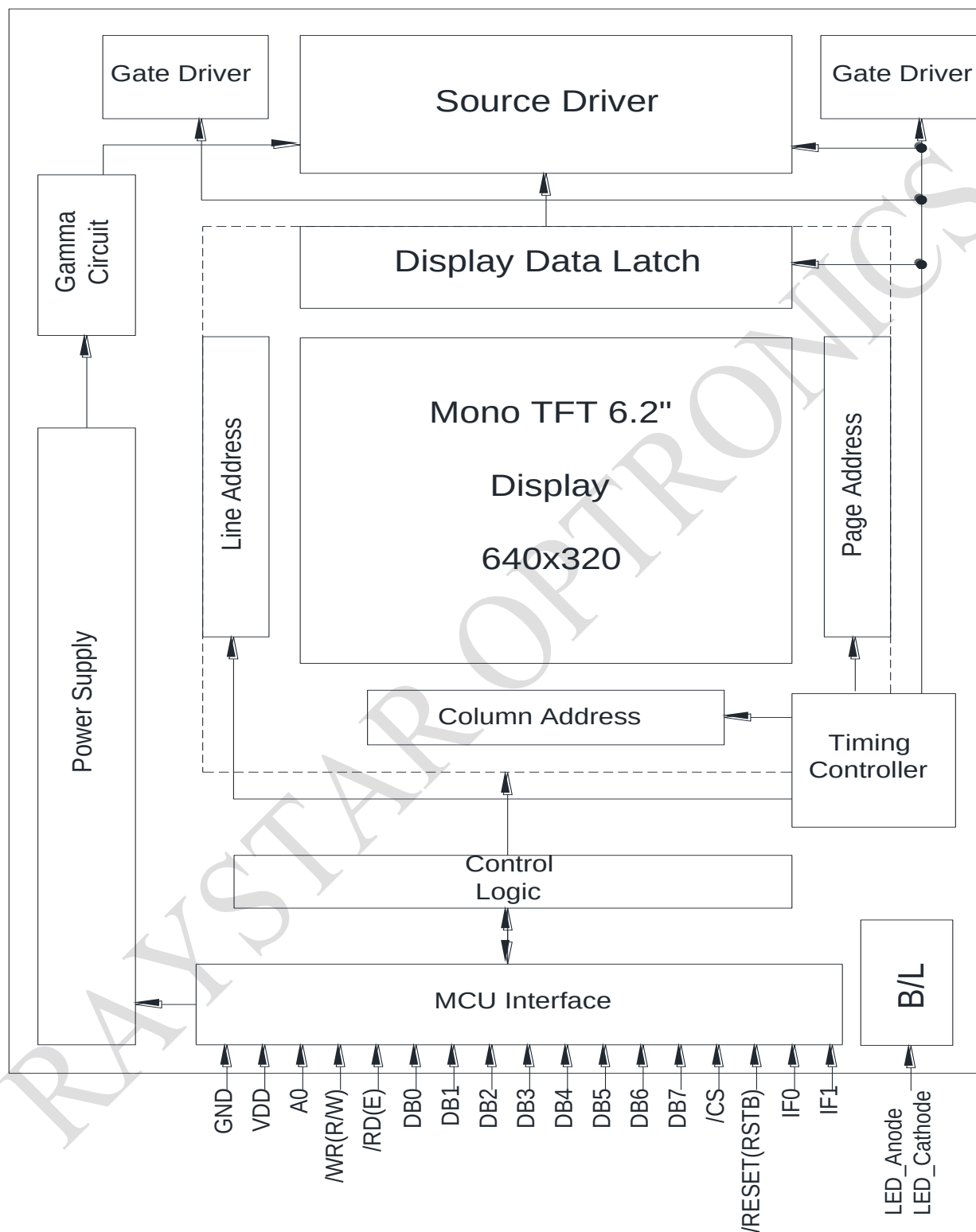
LED Light Bar connector is used for the the integral backlight system. The recommended model is “JST XH-3” manufactured by JST.

Pin No.	Symbol	I/O	Function	Remark
1	V _{LED+}	P	Power for LED backlight anode (A)	Red
3	V _{LED-}	P	Power for LED backlight cathode (K)	Black

5. Contour Drawing



6. Block Diagram

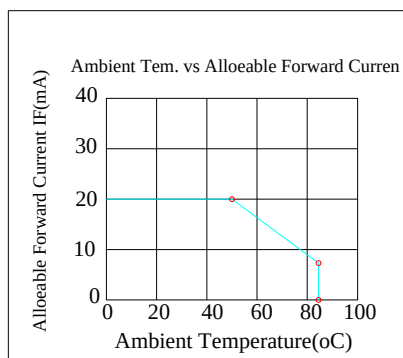


7. Absolute Maximum Ratings

Item	Symbol	Min	Typ	Max	Unit
Operating Temperature	TOP	-20	—	+70	°C
Storage Temperature	TST	-30	—	+80	°C

Note: Device is subject to be damaged permanently if stresses beyond those absolute maximum ratings listed above

- Temp. $\leq 60^{\circ}\text{C}$, 90% RH MAX. Temp. $> 60^{\circ}\text{C}$, Absolute humidity shall be less than 90% RH at 60°C



8. Electrical Characteristics

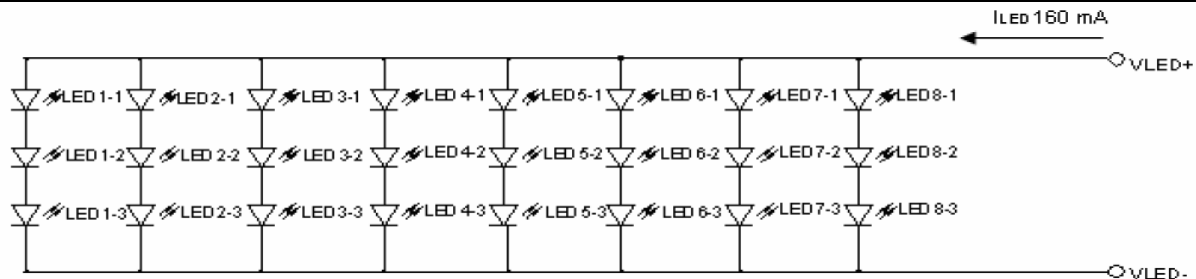
8.1. Operating conditions:

Item	Symbol	Condition	Min	Typ	Max	Unit	Remark
Supply Voltage For LCM	VDD	—	3.0	3.3	3.6	V	
Supply Current For LCM	IDD	—	—	25	38	mA	Note1
Power Consumption	—	—	—	83	137	mW	

Note1: This value is test for VDD=3.3V only

8.2. LED driving conditions

Parameter	Symbol	Min.	Typ.	Max.	Unit	Remark
LED current		-	160	-	mA	
Power Consumption		1392	-	1680	mW	
LED voltage	A-K	8.7	9.6	10.5	V	Note 1
LED Life Time		-	20,000	-	Hr	Note 2,3,4



Note 1 : Power supply the back light specification

Note 2 : Ta = 25 °C

Note 3 : Brightness to be decreased to 50% of the initial value

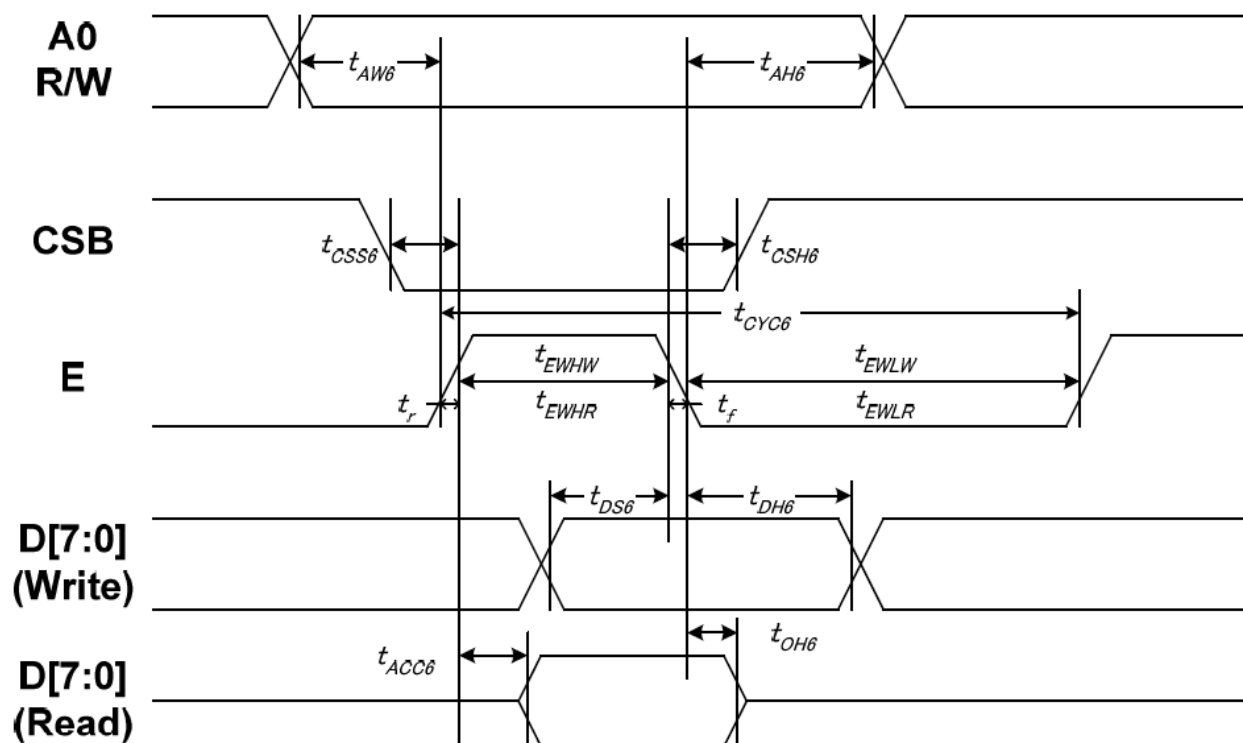
Note 4 : The single LED lamp case

9.DC CHARATERISTICS

Parameter	Symbol	Rating			Unit	Condition
		Min	Typ	Max		
Low level input voltage	V_{IL}	0	-	0.3VDD	V	
High level input voltage	V_{IH}	0.7VDD	-	VDD	V	

10.AC CHARACTERISTICS

10.1. System Bus Timing for 6800 Series MPU

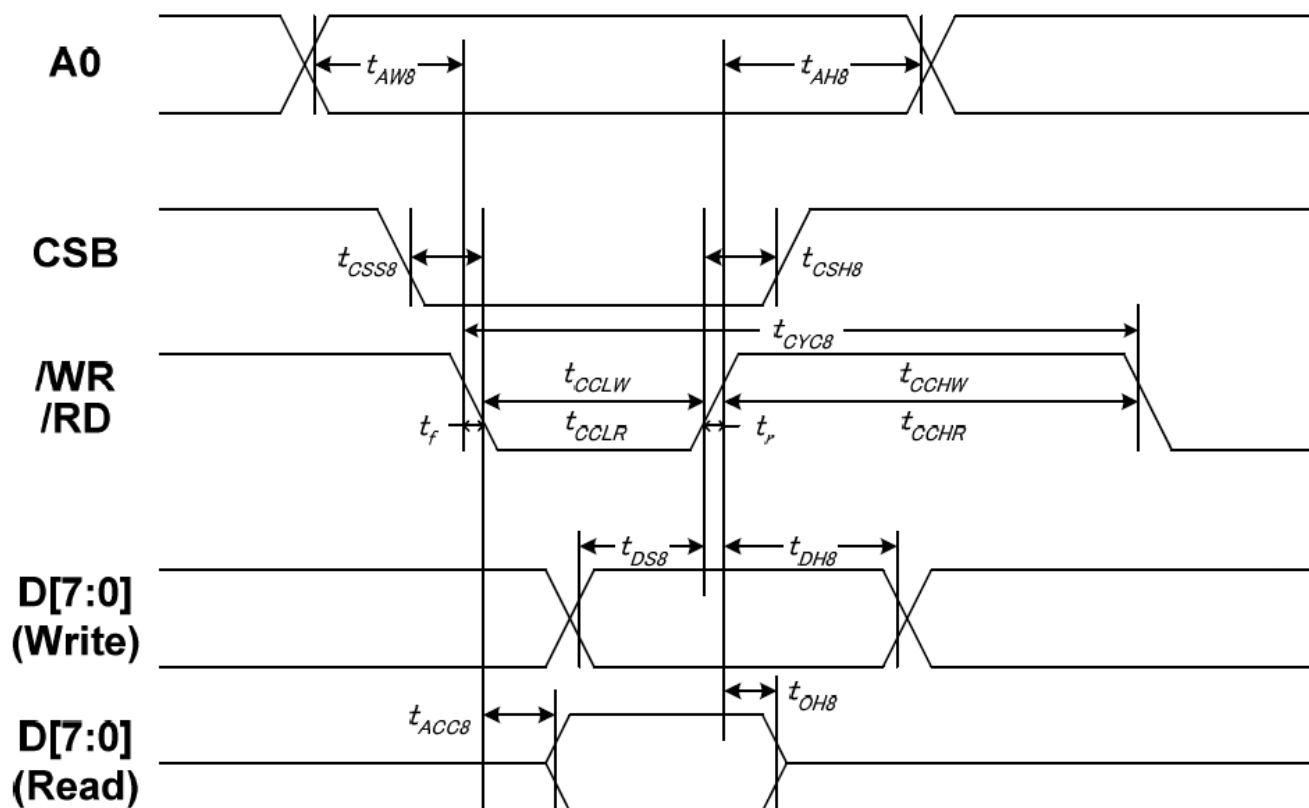


Item	Signal	Symbol	Condition	Min	Max	Unit
Address setup time	A0	tAW6	-	10	-	ns
Address hold time		tAH6	-	0	-	
System cycle time	E	tCYC6	-	200	-	
Enable L pulse width (WRITE)		tEWLW	-	100	-	
Enable H pulse width (WRITE)		tEWHW	-	100	-	
Enable L pulse width (READ)		tEWLR	-	130	-	
Enable H pulse width (READ)		tEWHR	-	130	-	
CSB setup time	CSB	tCSS6	-	100	-	
CSB hold time		tCSH6	-	100	-	
Write data setup time	D[7:0]	tDS6	-	70	-	
Write data hold time		tDH6	-	20	-	
Read data access time		tACC6	CL = 100 pF	-	80	
Read data output disable time		tOH6	CL = 100 pF	15	80	

Note:

1. The input signal rise time and fall time (t_r , t_f) is specified at 15 ns or less. When the system cycle time is extremely fast, $(t_r + t_f) \leq (t_{CYC8} - t_{CCLW} - t_{CCHW})$ for $(t_r + t_f) \leq (t_{CYC8} - t_{CCLR} - t_{CCHR})$ are specified.
2. All timing is specified using 20% and 80% of VDDI as the reference.
3. t_{CCLW} and t_{CCLR} are specified as the overlap between CSB being “L” and /WR and /RD being at the “L” level. CSB and /WR (or /RD) cannot act at the same time and CSB should be 100ns wider than /WR (or /RD).

10.2. System Bus Timing for 8080 Series MPU



Item	Signal	Symbol	Condition	Min	Max	Unit
Address setup time	A0	tAW8	-	10	-	ns
Address hold time		tAH8	-	0	-	
System cycle time		tCYC8	-	200	-	
/WR L pulse width (WRITE)	/WR	tCCLW	-	100	-	
/WR H pulse width (WRITE)		tCCHW	-	100	-	
/RD L pulse width (READ)	/RD	tCCLR	-	120	-	
/RD H pulse width (READ)		tCCHR	-	120	-	
CSB setup time	CSB	tCSS8	-	100	-	
CSB hold time		tCSH8	-	100	-	
Write data setup time	D[7:0]	tDS8	-	70	-	
Write data hold time		tDH8	-	20	-	
Read data access time		tACC8	CL = 100 pF	-	80	
Read data output disable time		tOH8	CL = 100 pF	15	80	

Note:

1. The input signal rise time and fall time (t_r , t_f) is specified at 15 ns or less. When the system cycle time

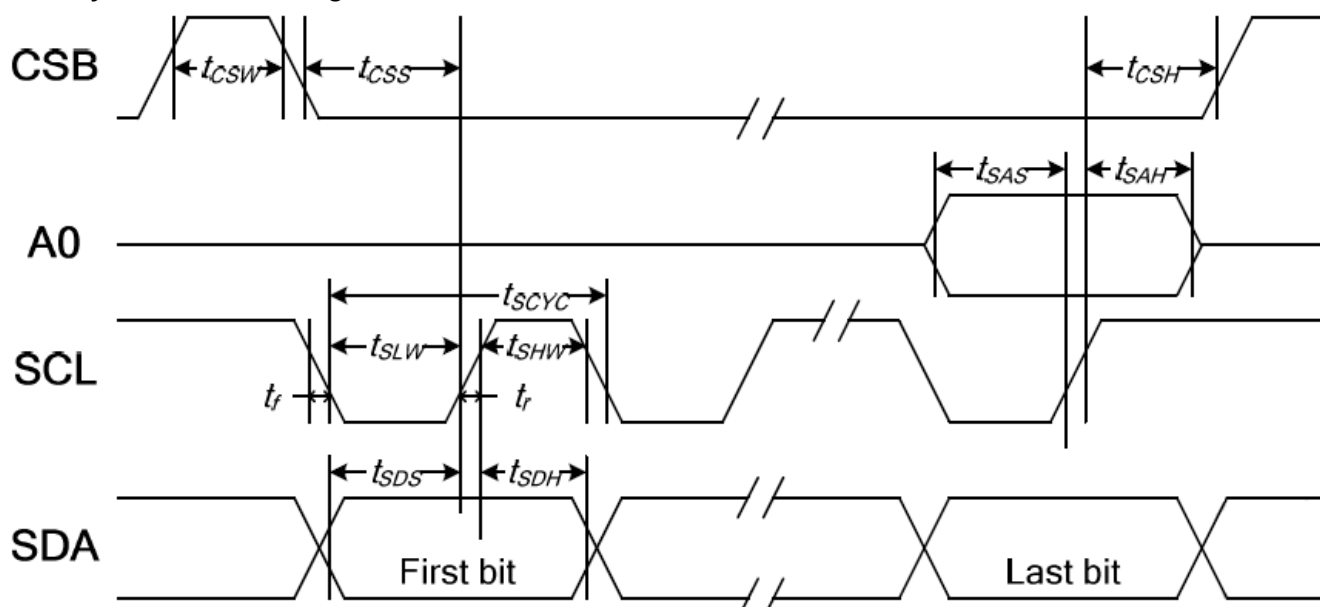
is extremely fast, $(t_r + t_f) \leq (t_{CYC8} - t_{CCLW} - t_{CCHW})$ for $(t_r + t_f) \leq (t_{CYC8} - t_{CCLR} - t_{CCHR})$ are specified.

2. All timing is specified using 20% and 80% of VDDI as the reference.

3. tCCLW and tCCLR are specified as the overlap between CSB being "L" and /WR and /RD being at the

"L" level. CSB and /WR (or /RD) cannot act at the same time and CSB should be 100ns wider than /WR (or /RD).

10.3. System Bus Timing for 4-Line Serial Interface

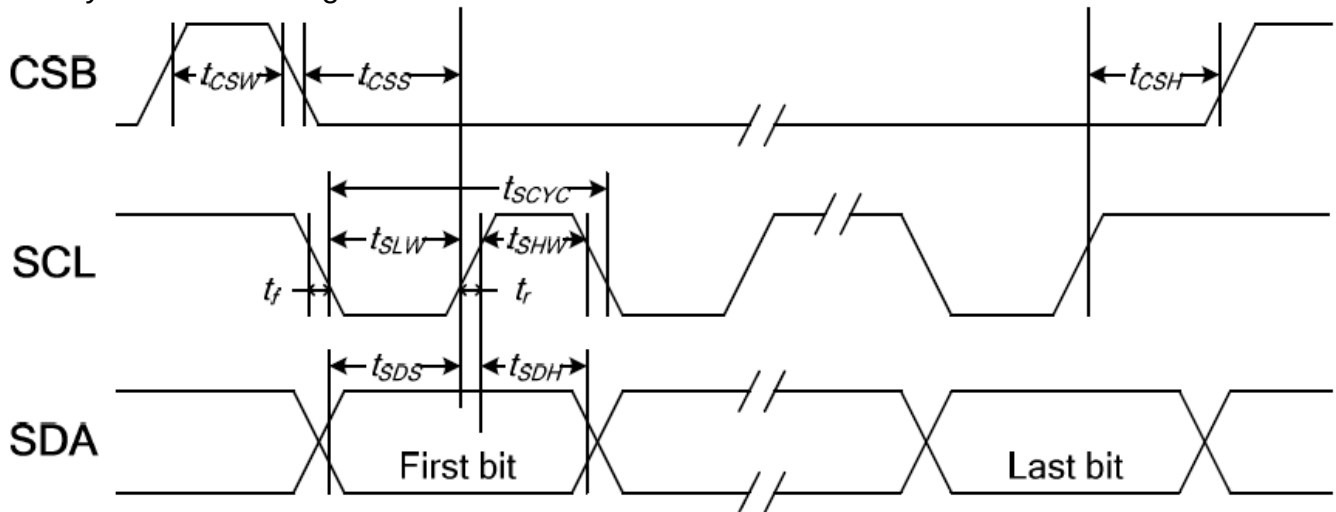


Item	Signal	Symbol	Condition	Min	Max	Unit
Serial clock period	SCL	t _{SCYC}	-	80	-	ns
SCL "H" pulse width		t _{SHW}	-	40	-	
SCL "L" pulse width		t _{SLW}	-	40	-	
Address setup time	A0	t _{SAS}	-	40	-	
Address hold time		t _{SAH}	-	40	-	
Data setup time	SDA	t _{SDS}	-	15	-	
Data hold time		t _{SDH}	-	20	-	
CSB-SCL time	CSB	t _{CSS}	-	40	-	
CSB-SCL time		t _{CSH}	-	40	-	
CSB "H" pulse width		t _{CSW}	-	15	-	

Note:

1. The input signal rise and fall time (t_r, t_f) are specified at 15 ns or less.
2. All timing is specified using 20% and 80% of VDDI as the standard.

10.4. System Bus Timing for 3-Line Serial Interface



Item	Signal	Symbol	Condition	Min	Max	Unit
Serial clock period	SCL	tSCYC	-	80	-	ns
SCL "H" pulse width		tSHW	-	40	-	
SCL "L" pulse width		tSLW	-	40	-	
Data setup time	SDA	tSDS	-	15	-	
Data hold time		tSDH	-	20	-	
CSB-SCL time	CSB	tCSS	-	40	-	
CSB-SCL time		tCSH	-	40	-	
CSB "H" pulse width		tCSW	-	15	-	

Note:

1. The input signal rise and fall time (t_r , t_f) are specified at 15 ns or less.
2. All timing is specified using 20% and 80% of VDDI as the standard.

11. Optical Characteristics

Item		Symbol	Temp	Condition.	Min	Typ.	Max.	Unit	Remark
Response time		Tr	25℃	θ=0°、φ=0	-	8	-	.ms	Note 3
		Tf	25℃		-	12	-		
Contrast ratio		CR	25℃	At optimized viewing angle	-	800	-	-	Note 4
Viewing angle (Gray Scale Inversion Direction)	Hor.	ΘR	25℃	CR ≧ 10	80			Deg.	Note 1 Note 2
		ΘL	25℃		80				
	Ver.	ΦB	25℃		80				
		ΦT	25℃		80				
Brightness		-	25℃	-	500	600	-	cd/m ²	Center of display

Ta=25±2℃, IL=160mA

Note 1: Definition of viewing angle range

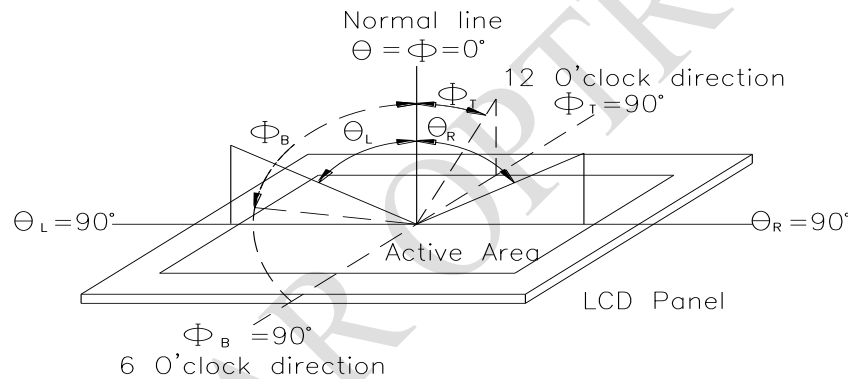


Fig.11.1. Definition of viewing angle

Note 2: Test equipment setup:

After stabilizing and leaving the panel alone at a driven temperature for 10 minutes, the measurement should be executed. Measurement should be executed in a stable, windless, and dark room. Optical specifications are measured by Topcon BM-7orBM-5 luminance meter 1.0° field of view at a distance of 50cm and normal direction.

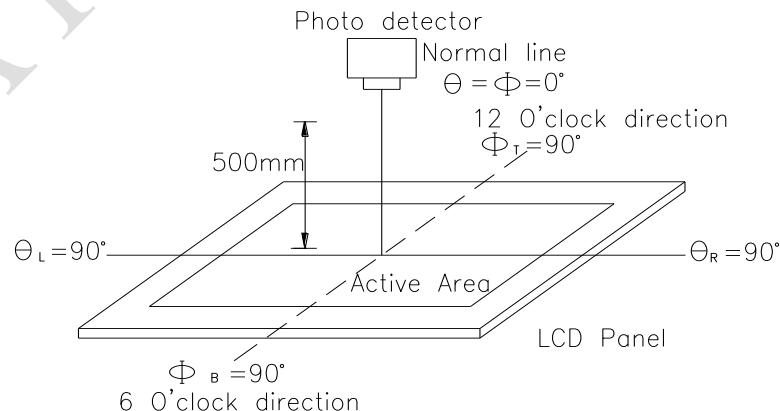
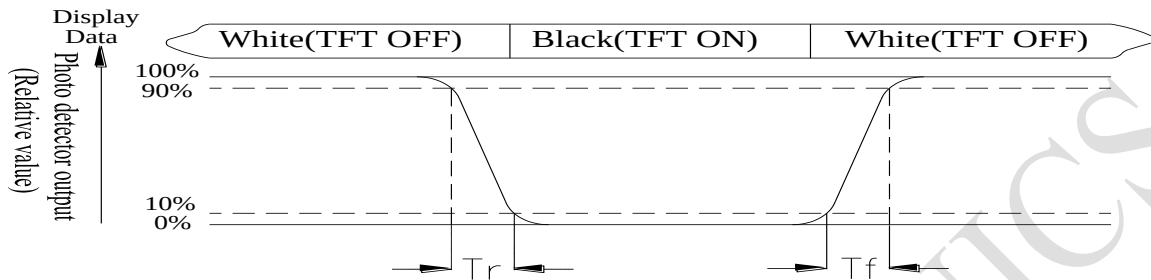


Fig. 11.2. Optical measurement system setup

Note 3: Definition of Response time:

The response time is defined as the LCD optical switching time interval between “White” state and “Black” state. Rise time, T_r , is the time between photo detector output intensity changed from 90% to 10%. And fall time, T_f , is the time between photo detector output intensity changed from 10% to 90%



Note 4: Definition of contrast ratio:

The contrast ratio is defined as the following expression.

$$\text{Contrast ratio (CR)} = \frac{\text{Luminance measured when LCD on the "White" state}}{\text{Luminance measured when LCD on the "Black" state}}$$

Note 5: White $V_i = V_{i50} \pm 1.5V$

Black $V_i = V_{i50} \pm 2.0V$

“±” means that the analog input signal swings in phase with VCOM signal.

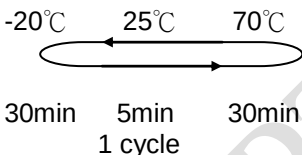
“±” means that the analog input signal swings out of phase with VCOM signal.

The 100% transmission is defined as the transmission of LCD panel when all the input terminals of module are electrically opened.

Note 6: Measured at the center area of the panel when all the input terminals of LCD panel are electrically opened.

12. Reliability

Content of Reliability Test (Wide temperature, -20°C~70°C)

Environmental Test			
Test Item	Content of Test	Test Condition	Note
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	—
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1
High Temperature/ Humidity Operation	The module should be allowed to stand at 60°C,90%RH max	60°C,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation 	-20°C/70°C 10 cycles	—
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude : 3 15mm Vibration Frequency : 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact) ,±800v(air), RS=330Ω CS=150pF 10 times	—

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

13.PACKAGE SPECIFICATION

LCM Model	RFP620A-6XW-DNN	LCM 包裝規格書 LCM Packaging Specifications	Approve	Check	Contact
Drawing NO.					
			DATE	初版	版次 Ver
			14'04/16	13'11/14	A

1.包裝材料規格表 (Packaging Material) :(per carton)

NO.	Item	Model	Dimensions	Quantity
1	成品 (LCM)	RFP620A-6XW-DNN		60
2	TRAY 盤 (2)	PKCA1XXXXXXXXXXXX0280	315*265mm	30
3	BP01 內盒(3)Product Box	PK3R1XXXXXXXXXXXX0001	332*280*100mm	6
4	泡棉(4)Foam	-----	283*230*8mm	6
5	外紙箱(5)Carton	PK4Q1XXXXXXXXXXXX0000	565*340*320mm	1
6				
7				
8				
9				

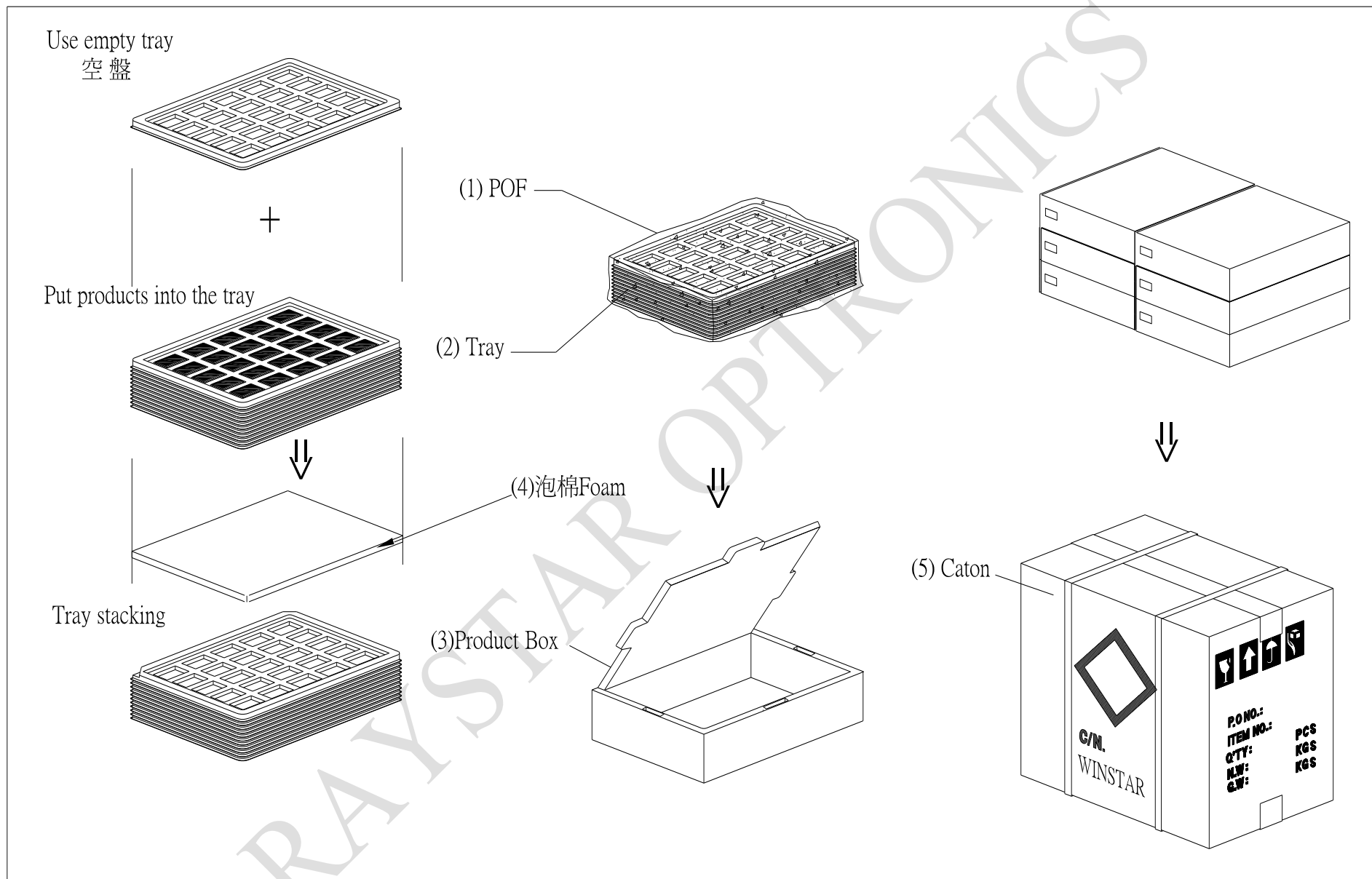
2.單箱數量規格表(Packaging Specifications and Quantity) :

(1)LCM quantity per box : no per tray 2 x no of tray 5 =10

(2)Total LCM quantity in carton : quantity per box 10 x no of boxes 6 =60

特 記 事 項 (REMARK)

1. Label Specifications : MOOEL: LOT NO : QUANTITY: CHECK:	
---	--



14.Initial Code For Reference

```
void Initial_code()
{
    Write_Command(0xae);
    Write_Data(0xa5);

    Write_Command(0x61);
    Write_Data(0x0f);
    Write_Data(0x04);
    Write_Data(0x02); // or 0xa5 (older version command)
    Write_Data(0xa5);

    Write_Command(0x62);
    Write_Data(0x00);
    Write_Data(0x3b);
    Write_Data(0x1b);
    Write_Data(0xa5);

    Write_Command(0x63);
    Write_Data(0x05);
    Write_Data(0x0f);
    Write_Data(0xa5);
    Write_Data(0xa5);

    Write_Command(0x24);
    Write_Data(0x01);
    Write_Data(0xa5);
    Write_Data(0xa5);
    Write_Data(0xa5);

    Write_Command(0x22);
    Write_Data(0x02);
    Write_Data(0xa5);
    Write_Data(0xa5);
    Write_Data(0xa5);

    Write_Command(0x91);
    Write_Data(0x00);
    Write_Data(0x21);
    Write_Data(0x23);
    Write_Data(0x24);

    Write_Command(0x92);
    Write_Data(0x27);
    Write_Data(0x28);
    Write_Data(0x29);
    Write_Data(0x2a);
}
```

```
Write_Command(0x93);  
Write_Data(0x2b);  
Write_Data(0x2c);  
Write_Data(0x2d);  
Write_Data(0x2e);
```

```
Write_Command(0x94);  
Write_Data(0x30);  
Write_Data(0x31);  
Write_Data(0x32);  
Write_Data(0x3f);
```

```
Write_Command(0x99);  
Write_Data(0x00);  
Write_Data(0x21);  
Write_Data(0x23);  
Write_Data(0x26);
```

```
Write_Command(0x9a);  
Write_Data(0x27);  
Write_Data(0x28);  
Write_Data(0x29);  
Write_Data(0x2a);
```

```
Write_Command(0x9b);  
Write_Data(0x2b);  
Write_Data(0x2c);  
Write_Data(0x2d);  
Write_Data(0x2e);
```

```
Write_Command(0x9c);  
Write_Data(0x30);  
Write_Data(0x35);  
Write_Data(0x3b);  
Write_Data(0x3f);
```

```
Write_Command(0x12);  
Write_Data(0xa5);
```

```
Write_Command(0x15);  
Write_Data(0xa5);
```

```
}
```

LCM Sample Estimate Feedback Sheet
Module Number : _____

1 、 Panel Specification :

1. Panel Type :	☐ Pass	☐ NG , _____
2. View Direction :	☐ Pass	☐ NG , _____
3. Numbers of Dots :	☐ Pass	☐ NG , _____
4. View Area :	☐ Pass	☐ NG , _____
5. Active Area :	☐ Pass	☐ NG , _____
6. Operating Temperature :	☐ Pass	☐ NG , _____
7. Storage Temperature :	☐ Pass	☐ NG , _____
8. Others :	_____	

2 、 Mechanical Specification :

1. PCB Size :	☐ Pass	☐ NG , _____
2. Frame Size :	☐ Pass	☐ NG , _____
3. Material of Frame :	☐ Pass	☐ NG , _____
4. Connector Position :	☐ Pass	☐ NG , _____
5. Fix Hole Position :	☐ Pass	☐ NG , _____
6. Backlight Position :	☐ Pass	☐ NG , _____
7. Thickness of PCB :	☐ Pass	☐ NG , _____
8. Height of Frame to PCB :	☐ Pass	☐ NG , _____
9. Height of Module :	☐ Pass	☐ NG , _____
10. Others :	☐ Pass	☐ NG , _____

3 、 Relative Hole Size :

1. Pitch of Connector :	☐ Pass	☐ NG , _____
2. Hole size of Connector :	☐ Pass	☐ NG , _____
3. Mounting Hole size :	☐ Pass	☐ NG , _____
4. Mounting Hole Type :	☐ Pass	☐ NG , _____
5. Others :	☐ Pass	☐ NG , _____

4 、 Backlight Specification :

1. B/L Type :	☐ Pass	☐ NG , _____
2. B/L Color :	☐ Pass	☐ NG , _____
3. B/L Driving Voltage (Reference for LED Type) :	☐ Pass	☐ NG , _____
4. B/L Driving Current :	☐ Pass	☐ NG , _____
5. Brightness of B/L :	☐ Pass	☐ NG , _____
6. B/L Solder Method :	☐ Pass	☐ NG , _____
7. Others :	☐ Pass	☐ NG , _____

>> Go to page 2 <<

Module Number : _____		
5 、 <u>Electronic Characteristics of Module</u> :		
1.Input Voltage :	☐ Pass	☐ NG , _____
2.Supply Current :	☐ Pass	☐ NG , _____
3.Driving Voltage for LCD :	☐ Pass	☐ NG , _____
4.Contrast for LCD :	☐ Pass	☐ NG , _____
5.B/L Driving Method :	☐ Pass	☐ NG , _____
6.Negative Voltage Output :	☐ Pass	☐ NG , _____
7.Interface Function :	☐ Pass	☐ NG , _____
8.LCD Uniformity :	☐ Pass	☐ NG , _____
9.ESD test :	☐ Pass	☐ NG , _____
10.Others :	☐ Pass	☐ NG , _____
6 、 <u>Summary</u> :		
Sales signature : _____ Customer Signature : _____ Date : / /		

LCM Sample Estimate Feedback Sheet		
Module Number : _____		
1 、 <u>Panel Specification</u> :		
1. Panel Type :	☐ Pass	☐ NG , _____
2. View Direction :	☐ Pass	☐ NG , _____
3. Numbers of Dots :	☐ Pass	☐ NG , _____
4. View Area :	☐ Pass	☐ NG , _____
5. Active Area :	☐ Pass	☐ NG , _____
6. Operating Temperature :	☐ Pass	☐ NG , _____
7. Storage Temperature :	☐ Pass	☐ NG , _____
8. Others : _____		
2 、 <u>Mechanical Specification</u> :		
1. PCB Size :	☐ Pass	☐ NG , _____
2. Frame Size :	☐ Pass	☐ NG , _____
3. Material of Frame :	☐ Pass	☐ NG , _____
4. Connector Position :	☐ Pass	☐ NG , _____
5. Fix Hole Position :	☐ Pass	☐ NG , _____
6. Backlight Position :	☐ Pass	☐ NG , _____
7. Thickness of PCB :	☐ Pass	☐ NG , _____
8. Height of Frame to PCB :	☐ Pass	☐ NG , _____
9. Height of Module :	☐ Pass	☐ NG , _____
10. Others :	☐ Pass	☐ NG , _____
3 、 <u>Relative Hole Size</u> :		
1. Pitch of Connector :	☐ Pass	☐ NG , _____
2. Hole size of Connector :	☐ Pass	☐ NG , _____
3. Mounting Hole size :	☐ Pass	☐ NG , _____
4. Mounting Hole Type :	☐ Pass	☐ NG , _____
5. Others :	☐ Pass	☐ NG , _____
4 、 <u>Backlight Specification</u> :		
1. B/L Type :	☐ Pass	☐ NG , _____
2. B/L Color :	☐ Pass	☐ NG , _____
3. B/L Driving Voltage (Reference for LED Type) : ☐ Pass ☐ NG , _____		
4. B/L Driving Current :	☐ Pass	☐ NG , _____
5. Brightness of B/L :	☐ Pass	☐ NG , _____
6. B/L Solder Method :	☐ Pass	☐ NG , _____
7. Others :	☐ Pass	☐ NG , _____

>> Go to page 2 <<

Module Number : _____

5 、 Electronic Characteristics of Module :

1.Input Voltage :	☐ Pass	☐ NG , _____
2.Supply Current :	☐ Pass	☐ NG , _____
3.Driving Voltage for LCD :	☐ Pass	☐ NG , _____
4.Contrast for LCD :	☐ Pass	☐ NG , _____
5.B/L Driving Method :	☐ Pass	☐ NG , _____
6.Negative Voltage Output :	☐ Pass	☐ NG , _____
7.Interface Function :	☐ Pass	☐ NG , _____
8.LCD Uniformity :	☐ Pass	☐ NG , _____
9.ESD test :	☐ Pass	☐ NG , _____
10.Others :	☐ Pass	☐ NG , _____

6 、 Summary :
Sales signature : _____

Customer Signature : _____

Date : / /